

650V N-Channel Enhancement Mode MOSFET

Description

The NP7N65G uses advanced high-voltage plane technology to provide excellent $R_{DS(ON)}$ and low gate charge. This power MOSFET is typically used for backup power supplies, LED lighting, and chargers.

General Features

- ◆ $V_{DS} = 650V$, $I_D = 7A$
 $R_{DS(ON)}(Typ.) = 1.15\Omega$ @ $V_{GS} = 10V$
- ◆ Fast switching time
- ◆ Low gate charge
- ◆ Low on-state resistance and have a high rugged avalanche characteristics
- ◆ Excellent package for good heat dissipation

Application

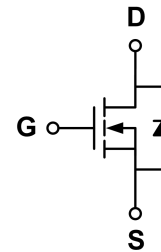
- ◆ Hard switched and high frequency circuits
- ◆ Uninterruptible power supply

Package

- ◆ TO-252-2L



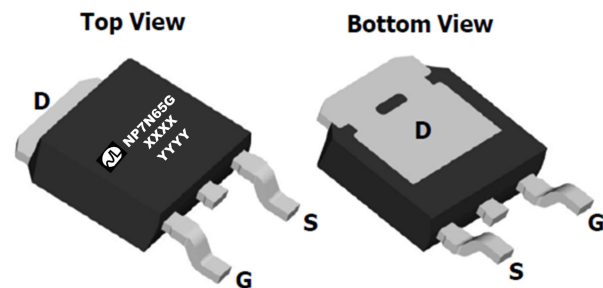
Schematic diagram



Marking and pin assignment

TO-252-2L

(Top View)



XXXX—Wafer Information

YYYY—Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP7N65G-G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter		symbol	limit	unit
Drain-source voltage		V_{DS}	650	V
Gate-source voltage		V_{GS}	±30	V
Continuous Drain Current	TC=25°C	I_D	7	A
	TC=100°C		5	
Pulsed Drain Current		I_{DM}	28	A
Avalanche energy(L=0.5mH)		E_{AS}	120	mJ
Maximum power dissipation	TC=25°C	P_D	60	W
Operating junction Temperature range		T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	650	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±30V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.1	4.0	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =4A	-	1.15	2.5	Ω
Diode Characteristics						
Diode Continuous Forward Current	I _S		-	-	7	A
Reverse Recovery Time	t _{rr}	I _F =3.5A, V _{GS} =0V	-	224	-	ns
Reverse Recovery Charge	Q _{rr}	dI/dt=100A/us	-	2.8	-	nC
Dynamic Characteristics²						
Intrinsic gate resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	1.7	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =50V f=1.0MHz	-	1184	-	pF
Output capacitance	C _{OSS}		-	41	-	
Reverse transfer capacitance	C _{RSS}		-	1.6	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =20V, V _{DS} =250V, R _G =25Ω, I _D =3.5A	-	21	-	ns
Turn-on Rise time	t _r		-	14	-	
Turn-off delay time	t _{D(OFF)}		-	55	-	
Turn-off Fall time	t _f		-	15	-	
Total gate charge	Q _g	V _{GS} =10V, I _D =3.5A V _{DS} =50V	-	19.6	-	nC
Gate-source charge	Q _{gs}		-	5.6	-	
Gate-drain charge	Q _{gd}		-	4.2	-	
Drain-Source Diode Characteristics						
Diode forward voltage	V _{SD}	I _{SD} =3.5A, V _{GS} =0V	-	0.8	1.4	V

Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

2: Guaranteed by design, not subject to production testing.

Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance-Junction to Case	R _{θJC}	1.1	°C/W
Thermal Resistance junction-to Ambient	R _{θJA}	45	

Typical Performance Characteristics

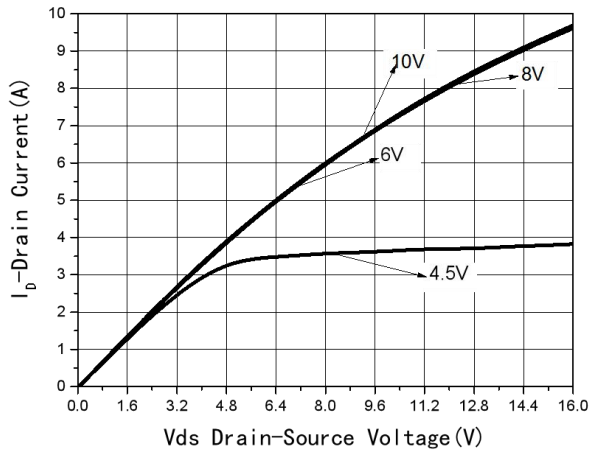


Fig1 Output Characteristics

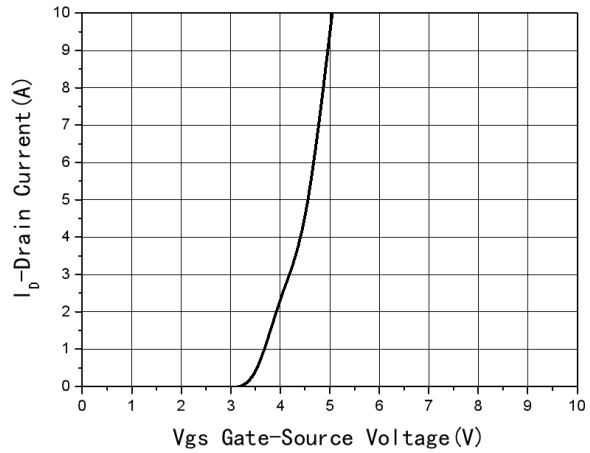


Fig2 Transfer Characteristics

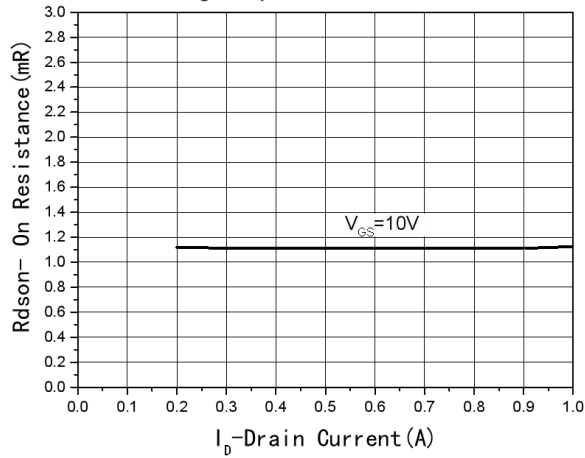


Fig3 $R_{DS(on)}$ -Drain current

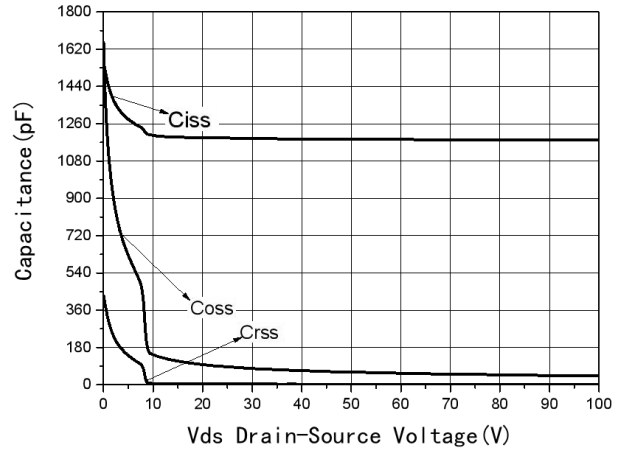
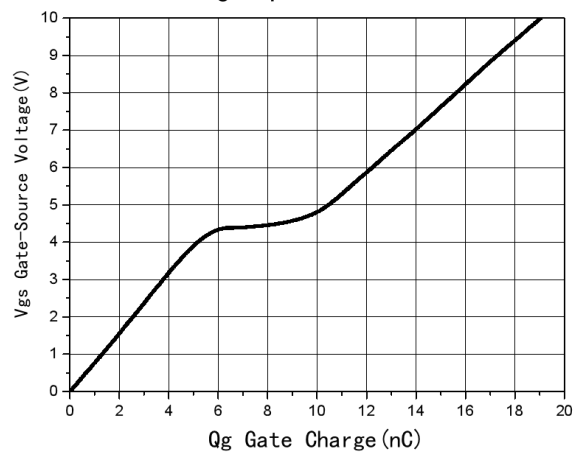
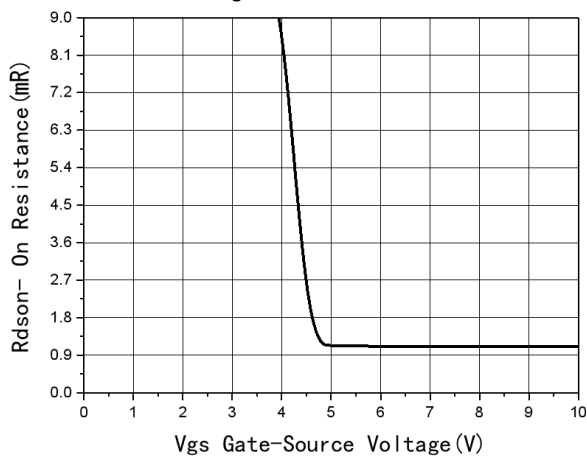


Fig4 Capacitance vs V_{DS}



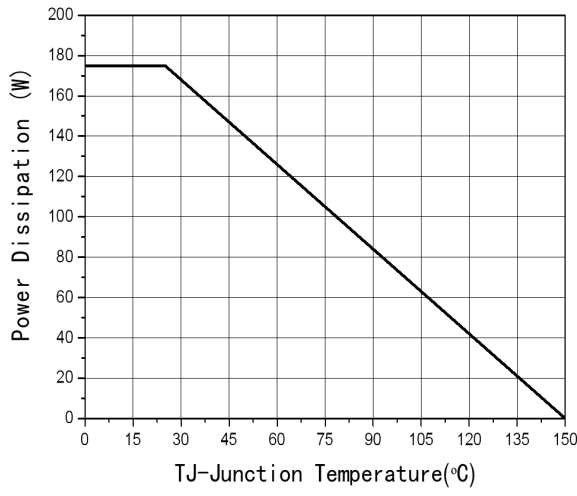


Fig7 Power De-rating

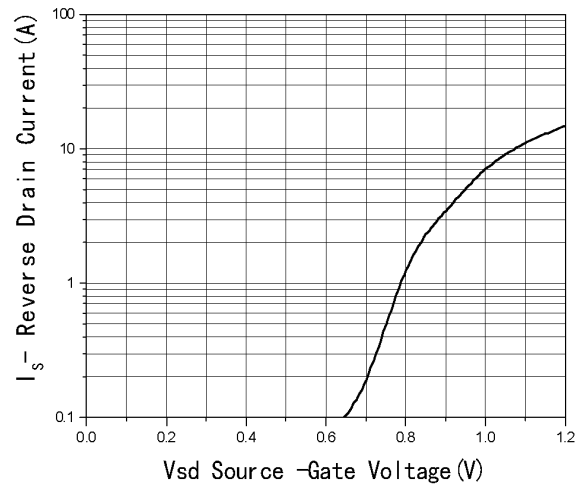
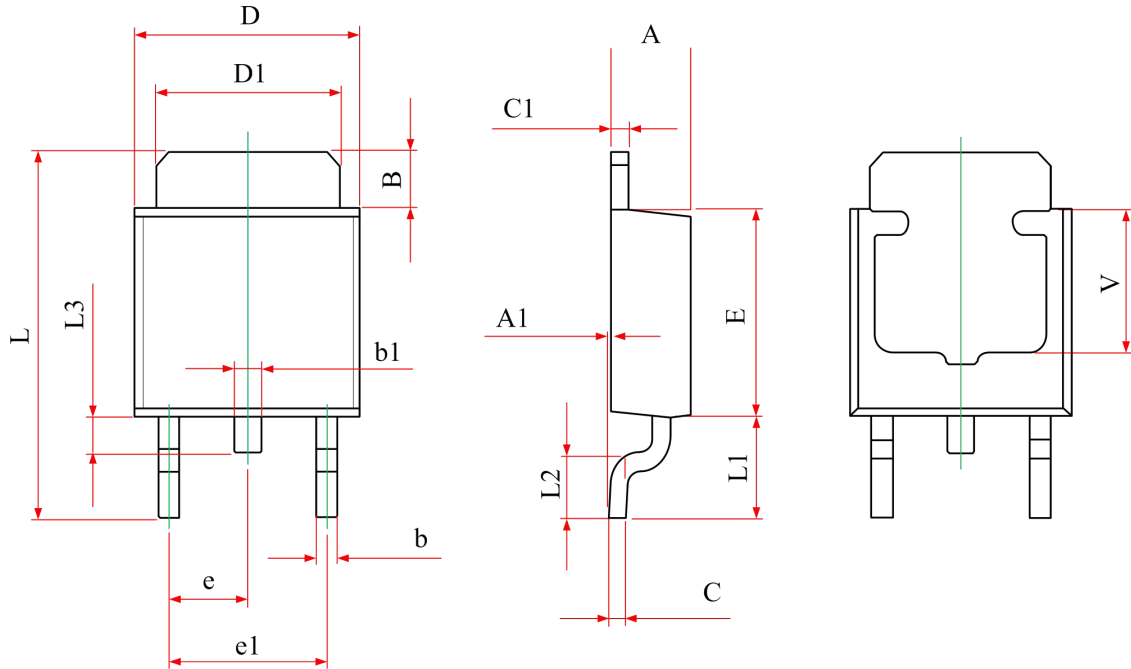


Fig8 Source-Drain Diode Forward

Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300TYP		0.091TYP	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800REF		0.150REF	